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FDD5612

60V N-Channel PowerTrench[®] MOSFET

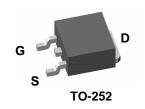
General Description

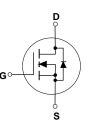
This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers.

These MOSFETs feature faster switching and lower gate charge than other MOSFETs with comparable $R_{DS(ON)}$ specifications. The result is a MOSFET that is easy and safer to drive (even at very high frequencies), and DC/DC power supply designs with higher overall efficiency.

Features

- 18 A, 60 V. $R_{DS(ON)} = 55 \text{ m}\Omega @ V_{GS} = 10 \text{ V}$ $R_{DS(ON)} = 64 \text{ m}\Omega @ V_{GS} = 6 \text{ V}$
- Optimized for use in high frequency DC/DC converters.
- Low gade charge.
- Very fast switching.





Absolute Maximum Ratings TA=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DSS}	Drain-Source Voltage		60	V
V _{GSS}	Gate-Source Voltage		±20	V
ID	Drain Current – Continuous	(Note 1)	18	A
		(Note 1a)	5.4	
	Drain Current – Pulsed		100	
P _D	Maximum Power Dissipation	(Note 1)	42	W
		(Note 1a)	3.8	
		(Note 1b)	1.6	
T _J , T _{STG}	Operating and Storage Junction Temp	erature Range	-55 to +175	°C

Incina				
R _{θJC}	Thermal Resistance, Junction-to-Case	(Note 1)	3.5	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient	(Note 1a)	40	°C/W
		(Note 1b)	96	

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
FDD5612	FDD5612	13"	16mm	2500 units

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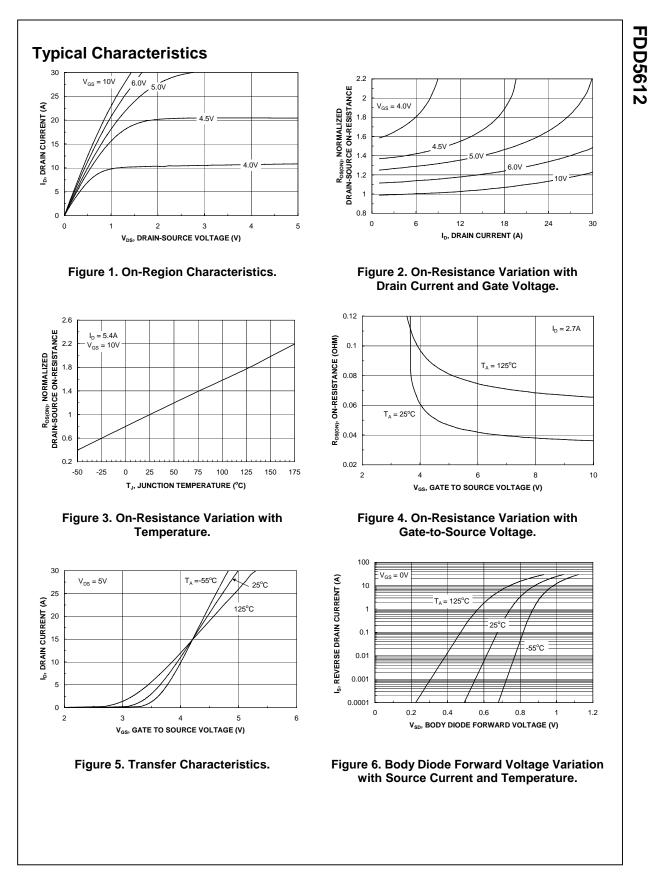
March 2015

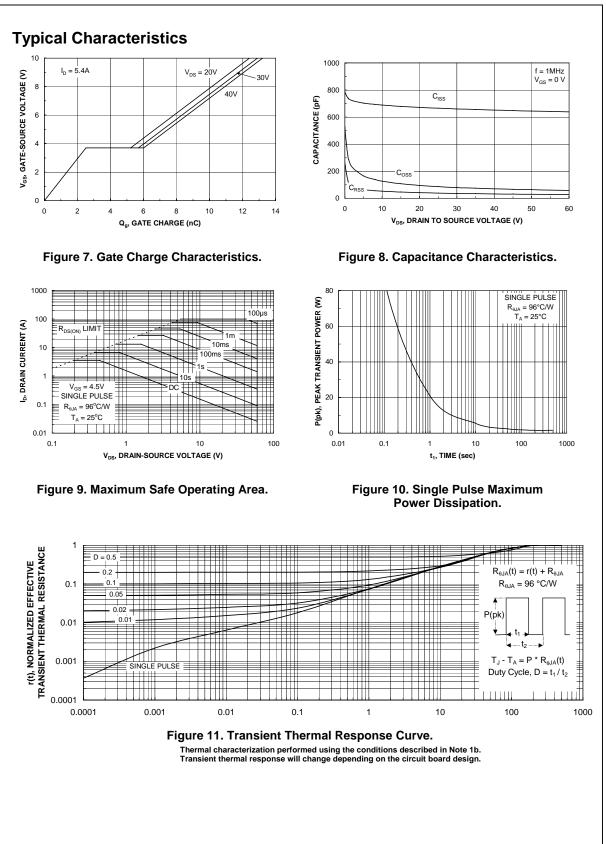
FDD5612

Avalanche EnergyBBBBIARMaximum Drain-Source Avalanche Current5.4AOff Characteristics BV_{DSS} Drain-Source Breakdown Voltage $V_{GS} = 0 \ V$, $I_D = 250 \ \mu A$ 60V ΔBV_{DSS} ΔT_J Breakdown Voltage Temperature Coefficient $I_D = 250 \ \mu A$, Referenced to 25° C62mV/°IbssZero Gate Voltage Drain Current $V_{DS} = 48 \ V$, $V_{GS} = 0 \ V$ 1 μA IcssrGate-Body Leakage, Forward $V_{GS} = 20 \ V$, $V_{DS} = 0 \ V$ 100nAIGSSRGate-Body Leakage, Reverse $V_{GS} = -20 \ V \ V_{DS} = 0 \ V$ -100nAOn Characteristics ΔT_J (Note 2) $V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$, Referenced to 25° C-6mV/° $V_{GS(th)}$ Gate Threshold Voltage $V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$ 12.43V $\Delta V_{GS(th)}$ Gate Threshold Voltage $I_D = 250 \ \mu A$, Referenced to 25° C-6mV/°	N_{DSS} Single Pulse Drain-Source Avalanche Energy AR $V_{DD} = 30 \text{ V}, I_D = 5.4 \text{ A}$ ARMaximum Drain-Source Avalanche Current $V_{DD} = 30 \text{ V}, I_D = 5.4 \text{ A}$ Off CharacteristicsBV_DSSDrain-Source Breakdown Voltage $V_{GS} = 0 \text{ V}, I_D = 250 \mu \text{ A}$ BV_DSSDrain-Source Breakdown Voltage Temperature Coefficient $I_D = 250 \mu \text{ A}, \text{ Referenced to } 25^{\circ}\text{ C}$ ΔT_J Breakdown Voltage Drain Current $V_{DS} = 48 \text{ V}, V_{GS} = 0 \text{ V}$ BSS Zero Gate Voltage Drain Current $V_{DS} = 48 \text{ V}, V_{DS} = 0 \text{ V}$ $GSSF$ Gate-Body Leakage, Forward $V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$ $GSSR$ Gate-Body Leakage, Reverse $V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$ $M_{GS(th)}$ Gate Threshold Voltage $I_D = 250 \mu \text{ A}, \text{ Referenced to } 25^{\circ}\text{ C}$ ΔT_J Gate Threshold Voltage $I_D = 250 \mu \text{ A}, \text{ Referenced to } 25^{\circ}\text{ C}$ ΔT_J Gate Threshold Voltage $I_D = 250 \mu \text{ A}, \text{ Referenced to } 25^{\circ}\text{ C}$ ΔT_J Gate Threshold Voltage $I_D = 5.4 \text{ A}, \text{ V}_{GS} = 10 \text{ V}, I_D = 5.4 \text{ A}, \text{ V}_{GS} = 10 \text{ V}, I_D = 5.4 \text{ A}, \text{ V}_{GS} = 10 \text{ V}, I_D = 5.4 \text{ A}, \text{ V}_{GS} = 10 \text{ V}, I_D = 5.4 \text{ A}, \text{ V}_{GS} = 10 \text{ V}, I_D = 5.4 \text{ A}, \text{ V}_{GS} = 10 \text{ V}, I_D = 5.4 \text{ A}, \text{ V}_{GS} = 10 \text{ V}, I_D = 5.4 \text{ A}, \text{ V}_{GS} = 10 \text{ V}, I_D = 5.4 \text{ A}, \text{ V}_{GS} = 10 \text{ V}, I_D = 5.4 \text{ A}, \text{ V}_{GS} = 5 \text{ V}, \text{ I}, \text{ D} = 5.4 \text{ A}, \text{ V}_{GS} = 5 \text{ V}, \text{ I}, \text{ D} = 5.4 \text{ A}, \text{ V}_{GS} = 5 \text{ V}, \text{ I}, \text{ D} = 5.4 \text{ A}, \text{ V}_{GS} = 5 \text{ V}, \text{ I}, \text{ D} = 5.4 \text{ A}, \text{ V}_{GS} = 5 \text{ V}, \text{ I}, \text{ D} = $	2.4 -6 36 42	1 100 -100 3	V mV/°C μA nA
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$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	$3V_{DSS}$ Drain-Source Breakdown Voltage $V_{GS} = 0 \text{ V}$, $I_D = 250 \mu \text{A}$ 60 ΔBV_{DSS} Breakdown Voltage Temperature Coefficient $I_D = 250 \mu \text{A}$, Referenced to 25°C 60 ΔT_J Coefficient $V_{DS} = 48 \text{ V}$, $V_{GS} = 0 \text{ V}$ 60 SSF Gate-Body Leakage, Forward $V_{GS} = 20 \text{ V}$, $V_{DS} = 0 \text{ V}$ 60 $GSSF$ Gate-Body Leakage, Reverse $V_{GS} = -20 \text{ V}$, $V_{DS} = 0 \text{ V}$ 60 $On Characteristics$ (Note 2) $V_{GS} = -20 \text{ V}$, $V_{DS} = 0 \text{ V}$ 60 $V_{GS(th)}$ Gate Threshold Voltage $V_{DS} = V_{GS}$, $I_D = 250 \mu \text{A}$ 1 ΔT_J Gate Threshold Voltage $V_{DS} = 10 \text{ V}$, $I_D = 5.4 \text{ A}$ 1 $\Delta V_{GS(th)}$ Static Drain-Source $V_{GS} = 10 \text{ V}$, $I_D = 5.4 \text{ A}$ 1 D_{GN} On-State Drain Current $V_{GS} = 10 \text{ V}$, $V_{DS} = 5 \text{ V}$ 20 $D_{(n)}$ On-State Drain Current $V_{GS} = 10 \text{ V}$, $V_{DS} = 5 \text{ V}$ 20 $D_{(n)}$ On-State Drain Current $V_{DS} = 5 \text{ V}$, $I_D = 5.4 \text{ A}$ 20 $D_{(n)}$ On-State Drain Current $V_{DS} = 5 \text{ V}$, $I_D = 5.4 \text{ A}$ 20 $D_{(n)}$ On-State Drain Current $V_{DS} = 30 \text{ V}$, $V_{CS} = 0 \text{ V}$,20 $D_{(n)}$ Input Capacitance $V_{DS} = 30 \text{ V}$, $V_{GS} = 0 \text{ V}$,0 $D_{(n)}$ Opticapacitance $V_{DS} = 30 \text{ V}$, $V_{CS} = 0 \text{ V}$,0	2.4 -6 36 42	1 100 -100	mV/°C μA nA nA
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	$3V_{DSS}$ Drain-Source Breakdown Voltage $V_{GS} = 0 \text{ V}$, $I_D = 250 \mu \text{A}$ 60 ΔBV_{DSS} Breakdown Voltage Temperature Coefficient $I_D = 250 \mu \text{A}$, Referenced to 25°C 60 ΔT_J Coefficient $V_{DS} = 48 \text{ V}$, $V_{GS} = 0 \text{ V}$ 60 SSF Gate-Body Leakage, Forward $V_{GS} = 20 \text{ V}$, $V_{DS} = 0 \text{ V}$ 60 $GSSF$ Gate-Body Leakage, Reverse $V_{GS} = -20 \text{ V}$, $V_{DS} = 0 \text{ V}$ 60 $On Characteristics$ (Note 2) $V_{GS} = -20 \text{ V}$, $V_{DS} = 0 \text{ V}$ 60 $V_{GS(th)}$ Gate Threshold Voltage $V_{DS} = V_{GS}$, $I_D = 250 \mu \text{A}$ 1 ΔT_J Gate Threshold Voltage $V_{DS} = 10 \text{ V}$, $I_D = 5.4 \text{ A}$ 1 $\Delta V_{GS(th)}$ Static Drain-Source $V_{GS} = 10 \text{ V}$, $I_D = 5.4 \text{ A}$ 1 D_{GN} On-State Drain Current $V_{GS} = 10 \text{ V}$, $V_{DS} = 5 \text{ V}$ 20 $D_{(n)}$ On-State Drain Current $V_{GS} = 10 \text{ V}$, $V_{DS} = 5 \text{ V}$ 20 $D_{(n)}$ On-State Drain Current $V_{DS} = 5 \text{ V}$, $I_D = 5.4 \text{ A}$ 20 $D_{(n)}$ On-State Drain Current $V_{DS} = 5 \text{ V}$, $I_D = 5.4 \text{ A}$ 20 $D_{(n)}$ On-State Drain Current $V_{DS} = 30 \text{ V}$, $V_{CS} = 0 \text{ V}$,20 $D_{(n)}$ Input Capacitance $V_{DS} = 30 \text{ V}$, $V_{GS} = 0 \text{ V}$,0 $D_{(n)}$ Opticapacitance $V_{DS} = 30 \text{ V}$, $V_{CS} = 0 \text{ V}$,0	2.4 -6 36 42	1 100 -100	mV/°C μA nA nA
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	LBVDSS ΔT_J Breakdown Voltage Temperature Coefficient $I_D = 250 \ \mu\text{A}$, Referenced to 25°C DSSZero Gate Voltage Drain Current $V_{DS} = 48 \ V$, $V_{GS} = 0 \ V$ GSSFGate–Body Leakage, Forward $V_{GS} = 20 \ V$, $V_{DS} = 0 \ V$ GSSRGate–Body Leakage, Reverse $V_{GS} = -20 \ V$, $V_{DS} = 0 \ V$ On Characteristics(Note 2) $V_{GS(th)}$ Gate Threshold Voltage $I_D = 250 \ \mu\text{A}$, Referenced to 25°C $\Delta V_{GS(th)}$ Gate Threshold Voltage $I_D = 250 \ \mu\text{A}$, Referenced to 25°C ΔT_J Temperature Coefficient $I_D = 250 \ \mu\text{A}$, Referenced to 25°C ΔT_J Static Drain–Source $V_{GS} = 10 \ V$, $I_D = 5.4 \ A$ $On-Resistance$ $V_{GS} = 10 \ V$, $I_D = 5.4 \ A$, $T_J = 125^{\circ}\text{C}$ $D(on)$ On–State Drain Current $V_{GS} = 10 \ V$, $V_{DS} = 5 \ V$ $D(on)$ On–State Drain Current $V_{DS} = 5 \ V$, $I_D = 5.4 \ A$ $Optimic$ Characteristics D_{ISS} Input Capacitance $V_{DS} = 30 \ V$, $V_{GS} = 0 \ V$,	2.4 -6 36 42	1 100 -100	μA nA nA
$\begin{array}{c c c c c c c } \hline l_{DSS} & Zero Gate Voltage Drain Current & V_{DS} = 48 V, & V_{GS} = 0 V & 1 & 1 & \muA \\ \hline l_{GSSF} & Gate-Body Leakage, Forward & V_{GS} = 20 V, & V_{DS} = 0 V & 100 & nA \\ \hline l_{GSSR} & Gate-Body Leakage, Reverse & V_{GS} = -20 V & V_{DS} = 0 V & -100 & nA \\ \hline On Characteristics & (Note 2) & & & & & & & & & & & & & & & & & & $	DSSZero Gate Voltage Drain Current $V_{DS} = 48 \text{ V}$, $V_{GS} = 0 \text{ V}$ GSSFGate-Body Leakage, Forward $V_{GS} = 20 \text{ V}$, $V_{DS} = 0 \text{ V}$ GSSRGate-Body Leakage, Reverse $V_{GS} = -20 \text{ V}$ $V_{DS} = 0 \text{ V}$ On Characteristics(Note 2) $V_{GS(th)}$ Gate Threshold Voltage $V_{DS} = V_{GS}$, $I_D = 250 \mu \text{A}$ 1 $\underline{AV_{GS(th)}}$ Gate Threshold Voltage $I_D = 250 \mu \text{A}$, Referenced to 25°C1 $\underline{AT_J}$ Temperature Coefficient $V_{GS} = 10 \text{ V}$, $I_D = 5.4 \text{ A}$ $V_{GS} = 6 \text{ V}$, $I_D = 5.4 \text{ A}$ $R_{DS(on)}$ Static Drain-Source $V_{GS} = 10 \text{ V}$, $I_D = 5.4 \text{ A}$ 20 $D(on)$ On-State Drain Current $V_{GS} = 10 \text{ V}$, $V_{DS} = 5 \text{ V}$ 20 D_{FS} Forward Transconductance $V_{DS} = 5 \text{ V}$, $I_D = 5.4 \text{ A}$ 20 $Dynamic Characteristics$ $V_{DS} = 30 \text{ V}$, $V_{GS} = 0 \text{ V}$,20 C_{ISS} Input Capacitance $V_{DS} = 30 \text{ V}$, $V_{GS} = 0 \text{ V}$,	-6 36 42	100 -100 3	nA nA V
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	GSSRGate-Body Leakage, Reverse $V_{GS} = -20 \ V \ V_{DS} = 0 \ V$ On Characteristics (Note 2)(Note 2) $V_{GS(th)}$ Gate Threshold Voltage $V_{DS} = V_{GS}$, $I_D = 250 \ \mu\text{A}$ 1 $V_{GS(th)}$ Gate Threshold Voltage $I_D = 250 \ \mu\text{A}$, Referenced to 25°C 1 ΔT_J Temperature Coefficient $V_{GS} = 10 \ V$, $I_D = 5.4 \ A$ 1 $R_{DS(on)}$ Static Drain-Source $V_{GS} = 10 \ V$, $I_D = 5.4 \ A$ $V_{GS} = 6 \ V$, $I_D = 5.4 \ A$ $D_{(on)}$ On-State Drain Current $V_{GS} = 10 \ V$, $V_{DS} = 5 \ V$ 20 P_{FS} Forward Transconductance $V_{DS} = 5 \ V$, $I_D = 5.4 \ A$ Dynamic Characteristics $V_{DS} = 30 \ V$, $V_{GS} = 0 \ V$,	-6 36 42	-100	nA V
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	On Characteristics (Solution (Note 2))(Note 2) $V_{GS(th)}$ Gate Threshold Voltage ΔT_J $V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$ 1 $\frac{V_{GS(th)}}{\Delta T_J}$ Gate Threshold Voltage Temperature Coefficient $I_D = 250 \ \mu A$, Referenced to 25° C1 $R_{DS(on)}$ Static Drain–Source On–Resistance $V_{GS} = 10 \ V$, $I_D = 5.4 \ A$ $V_{GS} = 6 \ V$, $I_D = 5.4 \ A$, $T_J = 125^{\circ}$ C20 $D_{(on)}$ On–State Drain Current $V_{GS} = 10 \ V$, $V_{DS} = 5 \ V$ 20 $D_{(on)}$ On–State Drain Current $V_{GS} = 10 \ V$, $V_{DS} = 5 \ V$ 20 D_{FS} Forward Transconductance $V_{DS} = 5 \ V$, $I_D = 5.4 \ A$ 20 D_{TS} Input Capacitance $V_{DS} = 5 \ V$, $I_D = 5.4 \ A$ 20 D_{TS} Input Capacitance $V_{DS} = 30 \ V$, $V_{GS} = 0 \ V$,20	-6 36 42	3	V
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	$ \begin{array}{ c c c c c c } \hline & Gate Threshold Voltage & V_{DS} = V_{GS}, & I_D = 250 \ \mu\text{A} & 1 \\ \hline & \underline{V_{GS(th)}} & Gate Threshold Voltage & I_D = 250 \ \mu\text{A}, Referenced to 25^{\circ}\text{C} \\ \hline & \underline{\Lambda}T_J & Temperature Coefficient & V_{DS} = 10 \ V, & I_D = 5.4 \ A \\ \hline & On-Resistance & V_{GS} = 10 \ V, & I_D = 5.4 \ A \\ \hline & V_{GS} = 10 \ V, & I_D = 5.4 \ A, \ T_J = 125^{\circ}\text{C} \\ \hline & V_{GS} = 10 \ V, & I_D = 5.4 \ A, \ T_J = 125^{\circ}\text{C} \\ \hline & V_{GS} = 10 \ V, & I_D = 5.4 \ A, \ T_J = 125^{\circ}\text{C} \\ \hline & V_{GS} = 10 \ V, & V_{DS} = 5 \ V & 20 \\ \hline & V_{FS} & Forward Transconductance & V_{DS} = 5 \ V, & I_D = 5.4 \ A \\ \hline & Dynamic Characteristics \\ \hline & C_{FS} & Input Capacitance & V_{DS} = 30 \ V, & V_{GS} = 0 \ V, \\ \hline & Output Capacitance & V_{DS} = 30 \ V, & V_{GS} = 0 \ V, \\ \hline & Output Capacitance & V_{DS} = 30 \ V, & V_{GS} = 0 \ V, \\ \hline & Output Capacitance & V_{DS} = 30 \ V, & V_{GS} = 0 \ V, \\ \hline & Output Capacitance & V_{DS} = 30 \ V, & V_{GS} = 0 \ V, \\ \hline & Output Capacitance & V_{DS} = 30 \ V, & V_{GS} = 0 \ V, \\ \hline & Output Capacitance & V_{DS} = 30 \ V, & V_{GS} = 0 \ V, \\ \hline & Output Capacitance & V_{DS} = 30 \ V, & V_{CS} = 0 \ V, \\ \hline & Output Capacitance & V_{DS} = 30 \ V, & V_{CS} = 0 \ V, \\ \hline & Output Capacitance & V_{DS} = 30 \ V, & V_{CS} = 0 \ V, \\ \hline & Output Capacitance & V_{DS} = 30 \ V, & V_{CS} = 0 \ V, \\ \hline & Output Capacitance & V_{DS} = 30 \ V, & V_{CS} = 0 \ V, \\ \hline & Output Capacitance & V_{DS} = 30 \ V, & V_{CS} = 0 \ V, \\ \hline & Output Capacitance & V_{CS} = 0 \ V, \\ \hline & Output Capacitance & V_{CS} = 0 \ V, \\ \hline & Output Capacitance & V_{CS} = 0 \ V, \\ \hline & Output Capacitance & V_{CS} = 0 \ V, \\ \hline & Output Capacitance & V_{CS} = 0 \ V, \\ \hline & Output Capacitance & V_{CS} = 0 \ V, \\ \hline & Output Capacitance & V_{CS} = 0 \ V, \\ \hline & Output Capacitance & V_{CS} \ V \ V_{CS} = 0 \ V, \\ \hline & Output Capacitance & V_{CS} \ V \ V_{CS} = 0 \ V, \\ \hline & Output Capacitance & V_{CS} \ V \ V \ V_{CS} \ V \ V \ V \ V \ V \ V \ V \ V \ V \ $	-6 36 42		
$\begin{array}{c c c c c c c c c c c c c c c c c c c $		-6 36 42		
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	36 42		mV/°C
$ \begin{array}{ c c c c c c c c } \hline On-Resistance & V_{GS} = 6 \ V, & I_D = 5 \ A \\ V_{GS} = 10 \ V, & I_D = 5 \ A \\ V_{GS} = 10 \ V, & I_D = 5 \ A \\ V_{GS} = 10 \ V, & V_{DS} = 5 \ V \\ \hline 20 & A \\ \hline 64 & 103 \\ \hline 75 & 110 \\ 64 & 103 \\ \hline 75 & 110 \\ 66 & 10 \\ \hline 75 & 110 \\ 66 & 10 \\ \hline 75 & 110 \\ 66 & 10 \\ \hline 75 & 110 \\ 66 & 10 \\ \hline 75 & 110 \\ 66 & 10 \\ \hline 75 & 110 \\ 66 & 10 \\ \hline 75 & 110 \\$	On-Resistance $V_{GS} = 6 \text{ V}$, $I_D = 5 \text{ A}$ $V_{GS} = 10 \text{ V}$, $I_D = 5.4 \text{ A}$, $T_J = 125^{\circ}\text{C}$ $D_{(on)}$ On-State Drain Current $V_{GS} = 10 \text{ V}$, $V_{DS} = 5 \text{ V}$ 20 P_{FS} Forward Transconductance $V_{DS} = 5 \text{ V}$, $I_D = 5.4 \text{ A}$ Oynamic Characteristics C_{ISS} Input Capacitance $V_{DS} = 30 \text{ V}$, $V_{GS} = 0 \text{ V}$,	42	55	
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	$D_{D(on)}$ On-State Drain Current $V_{GS} = 10 \text{ V}, V_{DS} = 5 \text{ V}$ 20 Q_{FS} Forward Transconductance $V_{DS} = 5 \text{ V}, I_D = 5.4 \text{ A}$ Oynamic Characteristics C_{ISS} Input Capacitance $V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V},$		64	mΩ
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	g_{FS} Forward Transconductance $V_{DS} = 5 \text{ V}$, $I_D = 5.4 \text{ A}$ Dynamic Characteristics C_{iss} Input Capacitance $V_{DS} = 30 \text{ V}$, $V_{GS} = 0 \text{ V}$,Quarter of the construction of the cons			Α
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	C_{iss} Input Capacitance $V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V},$	15		S
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	C_{iss} Input Capacitance $V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V},$			
In the number of the term of	C _{oss} Output Capacitance f = 1.0 MHz	660)	pF
		79		pF
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	C _{rss} Reverse Transfer Capacitance	36		pF
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Switching Characteristics (Note 2)			
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		8	16	ns
t_f Turn-Off Fall Time48ns Q_g Total Gate Charge $V_{DS} = 30 \text{ V}$, $I_D = 5.4 \text{ A}$,7.511nC Q_{gs} Gate-Source Charge $V_{GS} = 10 \text{ V}$ 2.5nC		4	8	ns
	_{d(off)} Turn–Off Delay Time	24	38	ns
Q_{gs} Gate-Source Charge $V_{GS} = 10 \text{ V}$ 2.5nC	f Turn–Off Fall Time	4	8	ns
	Q_g Total Gate Charge $V_{DS} = 30 \text{ V}, I_D = 5.4 \text{ A},$	7.5	11	nC
Qgd Gate-Drain Charge 3 nC	Q_{gs} Gate-Source Charge $V_{GS} = 10 V$	2.5		nC
	Q _{gd} Gate–Drain Charge	3		nC
Drain-Source Diode Characteristics and Maximum Patings	Drain–Source Diode Characteristics and Maximum Ratings			
Diani-Ourise Divue Sharasierishis anu waxiinuni Nalinys				Α
			2.7	
Drain Source Diede Characteristics and Maximum Patings	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	4 24 4 7.5 2.5	8 38 8 11	



2. Pulse Test: Pulse Width < 300µs, Duty Cycle < 2.0%





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